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(54) **MULTILAYER ELECTRONIC COMPONENT**

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(57) **ABSTRACT**

A multilayer electronic component includes: a body having first and second surfaces opposing each other in a first direction, and third and fourth surfaces connected to first and second surfaces and opposing each other in a second direction; a first external electrode including a first connection portion disposed on the third surface, a first band portion extending from the first connection portion onto a portion of the first surface, and a third band portion extending from the first connection portion onto a portion of the second surface; a second external electrode including a second connection portion disposed on the fourth surface, and a second band portion extending from the second connection portion onto a portion of the first surface; an insulating layer including a silicone-based resin and disposed on the first and second connection portions.

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